

INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION  
(PTO-1449)



ATTY. DOCKET NO.  
005920  
USA/FPS/MMCS/APC

SERIAL NO.  
09/943,383

APPLICANT  
SHANMUGASUNDRAM et al.

FILING DATE  
August 31, 2001

GROUP  
2823

## U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,901,313	05/04/99	Wolf et al.			09/02/97
	6,002,989	12/14/99	Shiba et al.			04/01/97
	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
	6,340,602	01/22/02	Johnson et al.			02/12/01
	6,345,288	02/05/02	Reed et al.			05/15/00
	6,368,879	04/09/02	Toprac			09/22/99
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	6,482,660	11/19/02	Conchieri et al.			03/19/01
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						Yes	No
	WO 99/59200	11/18/99	WIPO			X	
	WO 01/52319	07/19/01	WIPO			X	

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	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.
	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.
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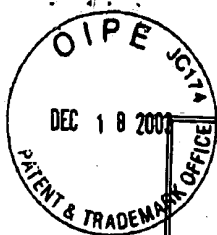
EXAMINER

DATE CONSIDERED

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	4,616,308	10/07/86	Morshedi et al.			12/02/85	
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	5,347,446	09/13/94	Iino et al.			02/10/92	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	EP 1 067 757	01/10/01	Europe			X	
	WO 01/33277	05/10/01	WO			X	
	WO 02/31613 A2	04/18/02	WO			X	
	WO 02/31613 A3	04/18/02	WO			X	
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	Levine, Martin D. 1985. <i>Vision in Man and Machine</i> . New York: McGraw-Hill, Inc. pp. ix-xii, 1-58.						
	Pilu, Maurizio. September 2001. "Undoing Page Curl Distortion Using Applicable Surfaces." <i>IEEE International Conference on Image Processing</i> . Thessalonica, Greece.						
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SHEET 1 OF 2

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	Miller, G. L., D. A. H. Robinson, and J. D. Wiley. July 1976. "Contactless measurement of semiconductor conductivity by radio frequency-free-carrier power absorption." <i>Rev. Sci. Instrum.</i> , Volume 47, No. 7. pp. 799 - 805.
	1999. "Contactless Bulk Resistivity/Sheet Resistance Measurement and Mapping Systems." <a href="http://www.Lehighton.com/fabtech1/index.html">www.Lehighton.com/fabtech1/index.html</a> .
	2000. "Microsense II Capacitance Gaging System." <a href="http://www.adetech.com">www.adetech.com</a> .

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SHEET 2 OF 2

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	El Chemali, Chadi et al. July/August 2000. "Multizone uniformity control of a chemical mechanical polishing process utilizing a pre- and postmeasurement strategy." <i>J. Vac. Sci. Technol.</i> Volume 18, No. 4. pp. 1287 - 1296.						
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	2002. "Microsense II - 5810: Non-Contact Capacitance Gaging Module." <a href="http://www.adetech.com">www.adetech.com</a> .						
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EXAMINER				DATE CONSIDERED 5/24/04			

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